



Welcome to **E-XFL.COM**

Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are **Embedded - System On Chip (SoC)**?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details	
Product Status	Obsolete
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	700MHz
Primary Attributes	FPGA - 462K Logic Elements
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA, FC (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5asxfb5g4f35c6n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Advantage	Supporting Feature
Lowest system cost	 Requires as few as four power supplies to operate Available in thermal composite flip chip ball-grid array (BGA) packaging Includes innovative features such as Configuration via Protocol (CvP), partial reconfiguration, and design security

Summary of Arria V Features

Table 2: Summary of Features for Arria V Devices

Feature	Description
Technology	 TSMC's 28-nm process technology: Arria V GX, GT, SX, and ST—28-nm low power (28LP) process Arria V GZ—28-nm high performance (28HP) process Lowest static power in its class (less than 1.2 W for 500K logic elements (LEs) at 85°C junction under typical conditions) 0.85 V, 1.1 V, or 1.15 V core nominal voltage
Packaging	 Thermal composite flip chip BGA packaging Multiple device densities with identical package footprints for seamless migration between different device densities Leaded⁽¹⁾, lead-free (Pb-free), and RoHS-compliant options
High-performance FPGA fabric	 Enhanced 8-input ALM with four registers Improved routing architecture to reduce congestion and improve compilation time
Internal memory blocks	 M10K—10-kilobits (Kb) memory blocks with soft error correction code (ECC) (Arria V GX, GT, SX, and ST devices only) M20K—20-Kb memory blocks with hard ECC (Arria V GZ devices only) Memory logic array block (MLAB)-640-bit distributed LUTRAM where you can use up to 50% of the ALMs as MLAB memory

Send Feedback

 $^{^{(1)}}$ Contact Altera for availability.

Feature	Description
FPGA General- purpose I/Os (GPIOs)	 1.6 Gbps LVDS receiver and transmitter 800 MHz/1.6 Gbps external memory interface On-chip termination (OCT) 3.3 V support (2)
External Memory Interface	 Memory interfaces with low latency: Hard memory controller-up to 1.066 Gbps Soft memory controller-up to 1.6 Gbps
Low-power high- speed serial interface	 600 Mbps to 12.5 Gbps integrated transceiver speed Less than 105 mW per channel at 6 Gbps, less than 165 mW per channel at 10 Gbps, and less than 170 mW per channel at 12.5 Gbps Transmit pre-emphasis and receiver equalization Dynamic partial reconfiguration of individual channels Physical medium attachment (PMA) with soft PCS that supports 9.8304 Gbps CPRI (Arria V GT and ST only) PMA with hard PCS that supports up to 9.8 Gbps CPRI (Arria V GZ only) Hard PCS that supports 10GBASE-R and 10GBASE-KR (Arria V GZ only)
HPS (Arria V SX and ST devices only)	 Dual-core ARM Cortex-A9 MPCore processor—up to 1.05 GHz maximum frequency with support for symmetric and asymmetric multiprocessing Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, serial peripheral interface (SPI), I2C interface, and up to 85 HPS GPIO interfaces System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers On-chip RAM and boot ROM HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller ARM CoreSight™ JTAG debug access port, trace port, and on-chip trace storage



 $^{^{(2)}~{\}rm Arria~V~GZ}$ devices support 3.3 V with a 3.0 V ${\rm V}_{\rm CCIO}.$

Resource		Member Code							
nesc	uice	A1	А3	A 5	A7	B1	В3	B5	В7
6 Gbps Transceiver		9	9	24	24	24	24	36	36
GPIO ⁽³⁾		416	416	544	544	704	704	704	704
LVD S	Transmi tter	67	67	120	120	160	160	160	160
3	Receiver	80	80	136	136	176	176	176	176
PCIe Hard IP Block		1	1	2	2	2	2	2	2
Hard Memory Controller		2	2	4	4	4	4	4	4

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 5: Package Plan for Arria V GX Devices

Member Code		72 mm)	F896 (31 mm)		F1152 (35 mm)		F1517 (40 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
A1	336	9	416	9	_	_	_	_
A3	336	9	416	9	_	_	_	_
A5	336	9	384	18	544	24	_	_
A7	336	9	384	18	544	24	_	_
B1	_	_	384	18	544	24	704	24
В3	_	_	384	18	544	24	704	24
B5	_	_	_	_	544	24	704	36
В7	_	_	_	_	544	24	704	36

Arria V GT

This section provides the available options, maximum resource counts, and package plan for the Arria V GT devices.



⁽³⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus[®] Prime software, the number of user I/Os includes transceiver I/Os.

Pose	Resource -		Member Code						
nesc			E 3	E 5	E 7				
Memory	M20K	11,700	19,140	28,800	34,000				
(Kb)	MLAB	2,594	4,245	4,718	5,306				
Variable-pred	Variable-precision DSP Block		1,044	1,092	1,139				
18 x 18 Multi	18 x 18 Multiplier		2,088	2,184	2,278				
PLL	PLL		20	24	24				
12.5 Gbps Tr	ansceiver	24	24	36	36				
GPIO ⁽⁷⁾		414	414	674	674				
LVDS	Transmitter	99	99	166	166				
LVDS	Receiver	108	108	168	168				
PCIe Hard IF	Block	1	1	1	1				

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 9: Package Plan for Arria V GZ Devices

Member Code	H780 (33 mm)			152 mm)	F1517 (40 mm)		
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	
E1	342	12	414	24	_	_	
E3	342	12	414	24	_	_	
E5	_	_	534	24	674	36	
E7	_	_	534	24	674	36	

Arria V SX

This section provides the available options, maximum resource counts, and package plan for the Arria V SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.



⁽⁷⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

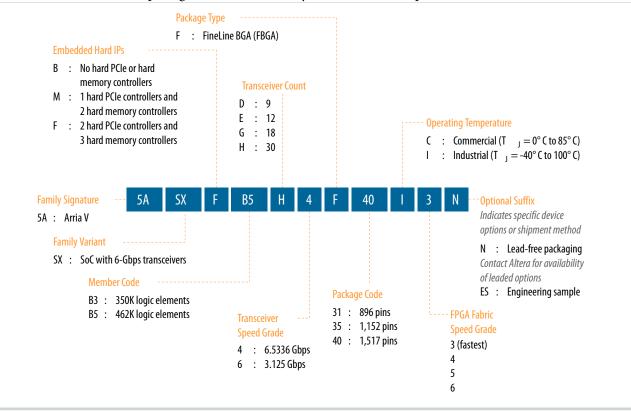
Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 4: Sample Ordering Code and Available Options for Arria V SX Devices

The -3 FPGA fabric speed grade is available only for industrial temperature devices.



Maximum Resources

Table 10: Maximum Resource Counts for Arria V SX Devices

Poso	urce	Member Code				
neso	ruice	В3	B5			
Logic Elements (LE)	(K)	350	462			
ALM		132,075	174,340			
Register	Register		697,360			
Memory (Kb)	M10K	17,290	22,820			
Memory (Ro)	MLAB	2,014	2,658			
Variable-precision D	Variable-precision DSP Block		1,090			
18 x 18 Multiplier		1,618	2,180			

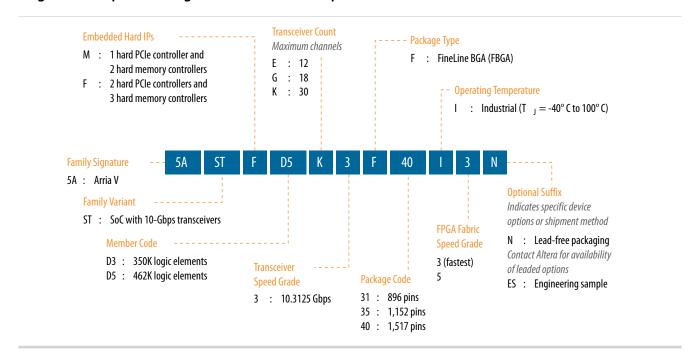


Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 5: Sample Ordering Code and Available Options for Arria V ST Devices



Maximum Resources

Table 12: Maximum Resource Counts for Arria V ST Devices

Reso	LINEO	Member Code				
Reso	ource	D3	D5			
Logic Elements (LE)	(K)	350	462			
ALM		132,075	174,340			
Register	Register		697,360			
Memory (Kb)	M10K	17,290	22,820			
Memory (Rb)	MLAB	2,014	2,658			
Variable-precision D	Variable-precision DSP Block		1,090			
18 x 18 Multiplier		1,618	2,180			
FPGA PLL	PGA PLL		14			
HPS PLL	HPS PLL		3			
Transceiver	6-Gbps	30	30			
Transcerver	10-Gbps ⁽⁹⁾	16	16			



Poso	ource	Member Code				
neso	raice	D3	D5			
FPGA GPIO ⁽¹⁰⁾		540	540			
HPS I/O		208	208			
LVDS	Transmitter	120	120			
LVD3	Receiver	136	136			
PCIe Hard IP Block	ock 2		2			
FPGA Hard Memory	FPGA Hard Memory Controller		GA Hard Memory Controller		3	
HPS Hard Memory C	Controller	1	1			
ARM Cortex-A9 MP	Core Processor	Dual-core	Dual-core			

• High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Transceiver Architecture in Arria V Devices
 Describes 10 Gbps channels usage conditions and SFF-8431 compliance requirements.

Package Plan

Table 13: Package Plan for Arria V ST Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Memb	F896 (31 mm)				F1152 (35 mm)			F1517 (40 mm)				
er Code	FPGA	HPS	ХС	VR	FPGA HPS		XCVR		FPGA	HPS	XCVR	
		I/O	6 Gbps	10 Gbps	GPIO	1/0	6 Gbps	10 Gbps	GPIO	I/O	6 Gbps	10 Gbps
D3	250	208	12	6	385	208	18	8	540	208	30	16
D5	250	208	12	6	385	208	18	8	540	208	30	16



⁽⁹⁾ Chip-to-chip connections only. For 10 Gbps channel usage conditions, refer to the Transceiver Architecture in Arria V Devices chapter.

⁽¹⁰⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

PLL Features

The PLLs in the Arria V devices support the following features:

- Frequency synthesis
- On-chip clock deskew
- Jitter attenuation
- Counter reconfiguration
- Programmable output clock duty cycles
- PLL cascading
- Reference clock switchover
- Programmable bandwidth
- Dynamic phase shift
- · Zero delay buffers

Fractional PLL

In addition to integer PLLs, the Arria V devices use a fractional PLL architecture. The devices have up to 16 PLLs, each with 18 output counters. One fractional PLL can use up to 18 output counters and two adjacent fractional PLLs share the 18 output counters. You can use the output counters to reduce PLL usage in two ways:

- Reduce the number of oscillators that are required on your board by using fractional PLLs
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

If you use the fractional PLL mode, you can use the PLLs for precision fractional-N frequency synthesis—removing the need for off-chip reference clock sources in your design.

The transceiver fractional PLLs that are not used by the transceiver I/Os can be used as general purpose fractional PLLs by the FPGA fabric.

FPGA General Purpose I/O

Arria V devices offer highly configurable GPIOs. The following list describes the features of the GPIOs:

- Programmable bus hold and weak pull-up
- $\bullet~$ LVDS output buffer with programmable differential output voltage (V $_{\rm OD}$) and programmable preemphasis
- On-chip parallel termination (R_T OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Unused voltage reference (VREF) pins that can be configured as user I/Os (Arria V GX, GT, SX, and ST only)
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture



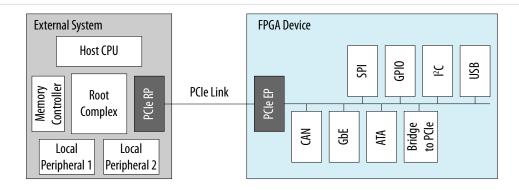
PCIe Gen1, Gen2, and Gen 3 Hard IP

Arria V devices contain PCIe hard IP that is designed for performance and ease-of-use. The PCIe hard IP consists of the MAC, data link, and transaction layers.

The PCIe hard IP supports PCIe Gen3, Gen 2, and Gen 1 end point and root port for up to x8 lane configuration.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in the following figure. The integrated multifunction support reduces the FPGA logic requirements by up to 20,000 LEs for PCIe designs that require multiple peripherals.

Figure 8: PCIe Multifunction for Arria V Devices



The Arria V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Arria V device completes loading the programming file for the rest of the device.

In addition, the PCIe hard IP in the Arria V device provides improved end-to-end datapath protection using ECC.

External Memory Interface

This section provides an overview of the external memory interface in Arria V devices.

Hard and Soft Memory Controllers

Arria V GX,GT, SX, and ST devices support up to four hard memory controllers for DDR3 and DDR2 SDRAM devices. Each controller supports 8 to 32 bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. For the Arria V SoC devices, an additional hard memory controller in the HPS supports DDR3, DDR2, and LPDDR2 SDRAM devices.

All Arria V devices support soft memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices, QDR II+, QDR II, and DDR II+ SRAM devices, and RLDRAM II devices for maximum flexibility.

Note: DDR3 SDRAM leveling is supported only in Arria V GZ devices.



24

External Memory Performance

Table 18: External Memory Interface Performance in Arria V Devices

Interface	Voltage	Hard Controller (MHz)	Soft Controller (MHz)		
interrace	(V)	Arria V GX, GT, SX, and ST	Arria V GX, GT, SX, and ST	Arria V GZ	
DDR3 SDRAM	1.5	533	667	800	
DDR3 3DRAM	1.35	533	600	800	
DDR2 SDRAM	1.8	400	400	400	
LPDDR2 SDRAM	1.2	_	400	_	
RLDRAM 3	1.2	_	_	667	
RLDRAM II	1.8	_	400	533	
	1.5	_	400	533	
QDR II+ SRAM	1.8	_	400	500	
	1.5	_	400	500	
QDR II SRAM	1.8	_	400	333	
	1.5	_	400	333	
DDR II+	1.8	_	400	_	
SRAM ⁽¹²⁾	1.5	_	400	_	

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Altera's External Memory Interface Spec Estimator tool.

HPS External Memory Performance

Table 19: HPS External Memory Interface Performance

The hard processor system (HPS) is available in Arria V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	533
DDR3 3DRAM	1.35	533
LPDDR2 SDRAM	1.2	333



⁽¹²⁾ Not available as Altera® IP.

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Altera's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

Arria V devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at less than 170 mW
- 10 Gbps transceivers at less than 165 mW
- 6 Gbps transceivers at less than 105 mW

Arria V transceivers are designed to be compliant with a wide range of protocols and data rates.

Transceiver Channels

The transceivers are positioned on the left and right outer edges of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.

The following figures are graphical representations of a top view of the silicon die, which corresponds to a reverse view for flip chip packages. Different Arria V devices may have different floorplans than the ones shown in the figures.



Figure 9: Device Chip Overview for Arria V GX and GT Devices

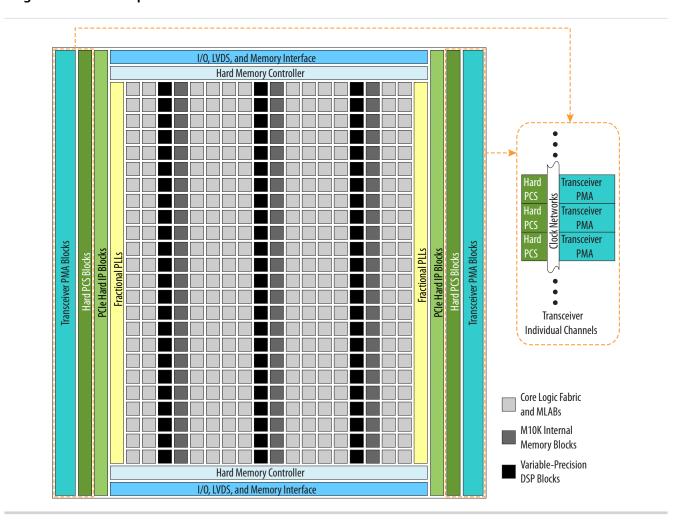
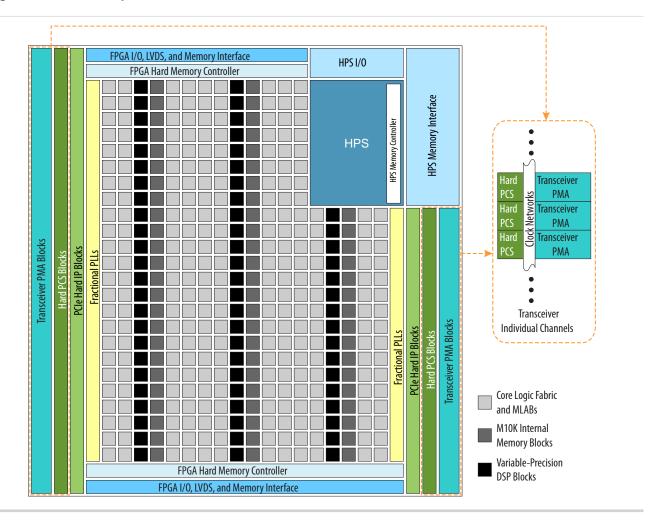




Figure 11: Device Chip Overview for Arria V SX and ST Devices



PMA Features

To prevent core and I/O noise from coupling into the transceivers, the PMA block is isolated from the rest of the chip—ensuring optimal signal integrity. For the transceivers, you can use the channel PLL of an unused receiver PMA as an additional transmit PLL.

Table 20: PMA Features of the Transceivers in Arria V Devices

Features	Capability
Backplane support	 Arria V GX, GT, SX, and ST devices—Driving capability at 6.5536 Gbps with up to 25 dB channel loss Arria V GZ devices—Driving capability at 12.5 Gbps with up to 16 dB channel loss
Chip-to-chip support	 Arria V GX, GT, SX, and ST devices—Up to 10.3125 Gbps Arria V GZ devices—Up to 12.5 Gbps



Features	Capability			
PLL-based clock recovery	Superior jitter tolerance			
Programmable serializer and deserializer (SERDES)	Flexible SERDES width			
Equalization and pre-emphasis	 Arria V GX, GT, SX, and ST devices—Up to 14.37 dB of pre-emphasis and up to 4.7 dB of equalization Arria V GZ devices—4-tap pre-emphasis and de-emphasis 			
Ring oscillator transmit PLLs	611 Mbps to 10.3125 Gbps			
LC oscillator ATX transmit PLLs (Arria V GZ devices only)	600 Mbps to 12.5 Gbps			
Input reference clock range	27 MHz to 710 MHz			
Transceiver dynamic reconfiguration	Allows the reconfiguration of a single channel without affecting the operation of other channels			

PCS Features

The Arria V core logic connects to the PCS through an 8, 10, 16, 20, 32, 40, 64, 66, or 67 bit interface, depending on the transceiver data rate and protocol. Arria V devices contain PCS hard IP to support PCIe Gen1, Gen2, and Gen3, GbE, Serial RapidIO (SRIO), GPON, and CPRI.

All other standard and proprietary protocols within the following speed ranges are also supported:

- 611 Mbps to 6.5536 Gbps—supported through the custom double-width mode (up to 6.5536 Gbps) and custom single-width mode (up to 3.75 Gbps) of the transceiver PCS hard IP.
- 6.5536 Gbps to 10.3125 Gbps—supported through dedicated 80 or 64 bit interface that bypass the PCS hard IP and connects the PMA directly to the core logic. In Arria V GZ, this is supported in the transceiver PCS hard IP.

Table 21: Transceiver PCS Features for Arria V GX, GT, ST, and SX Devices

PCS Support ⁽¹³⁾	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
Custom single- and double-width modes	0.611 to ~6.5536	Phase compensation FIFO	Word aligner8B/10B decoder
SRIO	1.25 to 6.25	Byte serializer 8B/10B encoder	Byte deserializer
Serial ATA	1.5, 3.0, 6.0	OB/10B chedder	Phase compensation FIFO



 $^{^{(13)}}$ Data rates above 6.5536 Gbps up to 10.3125 Gbps, such as 10GBASE-R, are supported through the soft PCS.

PCS Support ⁽¹³⁾	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature		
PCIe Gen1 (x1, x2, x4, x8) PCIe Gen2 ⁽¹⁴⁾ (x1, x2, x4)	2.5 and 5.0	 Phase compensation FIFO Byte serializer 8B/10B encoder PIPE 2.0 interface to the core logic 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO Rate match FIFO PIPE 2.0 interface to the core logic 		
GbE	1.25	Phase compensation FIFOByte serializer8B/10B encoder	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO Rate match FIFO 		
XAUI ⁽¹⁵⁾	3.125	 Phase compensation FIFO Byte serializer 8B/10B encoder XAUI state machine for bonding four channels 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO XAUI state machine for realigning four channels Deskew FIFO circuitry 		
SDI	0.27 ⁽¹⁶⁾ , 1.485, 2.97	Phase compensation FIFO Byte serializer	Byte deserializerPhase compensation FIFO		
GPON ⁽¹⁷⁾	1.25 and 2.5	byte serializer	• Fliase compensation FIFO		
CPRI ⁽¹⁸⁾	0.6144 to 6.144	 Phase compensation FIFO Byte serializer 8B/10B encoder TX deterministic latency 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO RX deterministic latency 		



⁽¹³⁾ Data rates above 6.5536 Gbps up to 10.3125 Gbps, such as 10GBASE-R, are supported through the soft PCS.

PCIe Gen2 is supported only through the PCIe hard IP.

⁽¹⁵⁾ XAUI is supported through the soft PCS.

⁽¹⁶⁾ The 0.27 Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

 $^{^{\}left(17\right) }$ The GPON standard does not support burst mode.

⁽¹⁸⁾ CPRI data rates above 6.5536 Gbps, such as 9.8304 Gbps, are supported through the soft PCS.

SoC with HPS

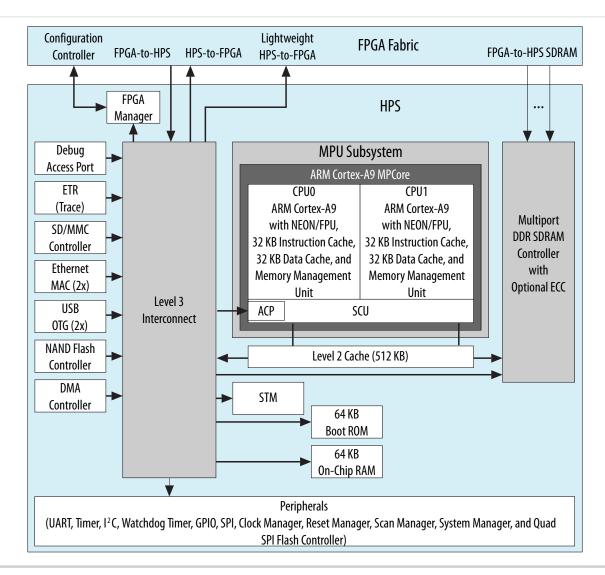
Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core ARM Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

Figure 12: HPS with Dual-Core ARM Cortex-A9 MPCore Processor





System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals to interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports ARM CoreSight debug and core traces to facilitate software development.

HPS-FPGA AXI Bridges

The HPS-FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA[®]) Advanced eXtensible Interface (AXITM) specifications, consist of the following bridges:

- FPGA-to-HPS AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to slaves in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS-FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon[®] Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features. The SDRAM controller subsystem supports DDR2, DDR3, or LPDDR2 devices up to 4 Gb in density operating at up to 533 MHz (1066 Mbps data rate).

FPGA Configuration and Processor Booting

The FPGA fabric and HPS in the SoC are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power, or shut down the entire FPGA fabric to reduce total system power.



You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or partially reconfigure the FPGA fabric at any time under software control. The HPS can also configure other FPGAs on the board through the FPGA configuration controller.
- You can power up both the HPS and the FPGA fabric together, configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

Note: Although the FPGA fabric and HPS are on separate power domains, the HPS must remain powered up during operation while the FPGA fabric can be powered up or down as required.

Related Information

- Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines
 Provides detailed information about power supply pin connection guidelines and power regulator sharing.
- Arria V GZ Device Family Pin Connection Guidelines
 Provides detailed information about power supply pin connection guidelines and power regulator sharing.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Qsys system integration tool in the Quartus Prime software.

For software development, the ARM-based SoC devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Altera SoCs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux, VxWorks®, and other operating systems is available for the SoCs. For more information on the operating systems support availability, contact the Altera sales team.

You can begin device-specific firmware and software development on the Altera SoC Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board that runs on a PC. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Related Information

Altera Worldwide Sales Support

Dynamic and Partial Reconfiguration

The Arria V devices support dynamic reconfiguration and partial reconfiguration.

Dynamic Reconfiguration

The dynamic reconfiguration feature allows you to dynamically change the transceiver data rates, PMA settings, or protocols of a channel, without affecting data transfer on adjacent channels. This feature is ideal for applications that require on-the-fly multiprotocol or multirate support. You can reconfigure the PMA, PCS, and PCIe hard IP blocks with dynamic reconfiguration.



Partial Reconfiguration

Note: Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Altera for support.

Partial reconfiguration allows you to reconfigure part of the device while other sections of the device remain operational. This capability is important in systems with critical uptime requirements because it allows you to make updates or adjust functionality without disrupting services.

Apart from lowering cost and power consumption, partial reconfiguration increases the effective logic density of the device because placing device functions that do not operate simultaneously is not necessary. Instead, you can store these functions in external memory and load them whenever the functions are required. This capability reduces the size of the device because it allows multiple applications on a single device—saving the board space and reducing the power consumption.

Altera simplifies the time-intensive task of partial reconfiguration by building this capability on top of the proven incremental compile and design flow in the Quartus Prime design software. With the Altera solution, you do not need to know all the intricate device architecture details to perform a partial reconfiguration.

Partial reconfiguration is supported through the FPP x16 configuration interface. You can seamlessly use partial reconfiguration in tandem with dynamic reconfiguration to enable simultaneous partial reconfiguration of both the device core and transceivers.

Enhanced Configuration and Configuration via Protocol

Table 23: Configuration Modes and Features of Arria V Devices

Arria V devices support 1.8 V, 2.5 V, 3.0 V, and 3.3 V⁽¹⁹⁾ programming voltages and several configuration modes.

Mode	Data Width	Max Clock Rate (MHz)	Max Datal Rate (Mbps)	Decompression		Partial econfiguratio (20)	Remote System Update
AS through the EPCS and EPCQ serial configuration device	1 bit, 4 bits	100	_	Yes	Yes	_	Yes
PS through CPLD or external microcontroller	1 bit	125	125	Yes	Yes	_	_



⁽¹⁹⁾ Arria V GZ does not support 3.3 V.

⁽²⁰⁾ Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Altera for support.

Date	Version	Changes
July 2012	2.1	 Added –I3 speed grade to Figure 1 for Arria V GX devices. Updated the 6-Gbps transceiver speed from 6.553 Gbps to 6.5536 Gbps in Figure 3 and Figure 1.
June 2012	2.0	 Restructured the document. Added the "Embedded Memory Capacity" and "Embedded Memory Configurations" sections. Added Table 1, Table 3, Table 12, Table 15, and Table 16. Updated Table 2, Table 4, Table 5, Table 6, Table 7, Table 8, Table 9, Table 10, Table 11, Table 13, Table 14, and Table 19. Updated Figure 1, Figure 2, Figure 3, Figure 4, and Figure 8. Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections. Text edits throughout the document.
February 2012	1.3	 Updated Table 1–7 and Table 1–8. Updated Figure 1–9 and Figure 1–10. Minor text edits.
December 2011	1.2	Minor text edits.
November 2011	1.1	 Updated Table 1–1, Table 1–2, Table 1–3, Table 1–4, Table 1–6, Table 1–7, Table 1–9, and Table 1–10. Added "SoC FPGA with HPS" section. Updated "Clock Networks and PLL Clock Sources" and "Ordering Information" sections. Updated Figure 1–5. Added Figure 1–6. Minor text edits.
August 2011	1.0	Initial release.

